

Sub. : Extension for Expression of Interest (EOI) for the Procurement of “Wire Bonding Machine”

Ref. No. : CBMR/ PUR/ 1168/ 2025

Dated: 23.01.2026

This Expression of Interest (EOI) invites applications from the reputed OEMs (original equipment manufacturers) for the procurement of “Wire Bonding Machine” by the Centre. Main features of the instrument as follows:

Requirement of a Wire Bonding Machine

For Wire Bonding of Fabricated Electronic Chips with Gold-coated PCB Carrier or various packages (TO, ceramic packages etc.).

Electrode Type: Gold, Platinum, Silver, ITO, Aluminum

Substrates: Glass, Silicon, Polyimide, Alumina, FR4, etc.

Features:

- Wedge-Wedge, Wedge-Ball Bonding, Ribbon Wedge Bonding.
- Capable of bonding with wire diameters of 0.7 mil to 3.0 mil and ribbons 1.2 (W) x 0.5 (T) to 10 (W) x 1.0 (T) in mils with essential tools or better. (1 mil = 25.4 μm).
- Gold and Aluminium Wire, Optional: Copper Wire.
- Thermosonic/Ultrasonic wire bonding.
- Adjustable Height Sample Stage including heating option.
- Microscope up to 50x magnification or higher.
- Semi-automatic Motorized Y & Z Axis with Manual Options.

General information / conditions / instruction to prospective bidders:

The scope of work includes the supply & installation of Wire Bonding Machine. Firms having done similar work can apply along with documentary evidence for work done in the past in government / private sector. The firm should also meet other criteria given below and is required to submit all supporting documents relating to the credentials / technical capabilities / financial standings and track along with their EoI as follows.

- a) Name of the firm with their constitution/proprietorship/partnership details etc. with the date of establishment/registration. Please submit the Articles of Association with the application.
- b) List of similar equipment supplied successfully in the last 5 years in Government research labs, other Government organizations and to Private Agencies along with brief details of the work. Enclose relevant document / certificate to ascertain the satisfactory completion of the work / service provided.

- c) List of employees in the firm, who will take up the requisite job/service listed above, their area of expertise and nature of their work in last five years.
- d) The list of work in hand, nature of work, cost, date of start and competition with present progress and the contact details of the clients.
- e) Proof of Turnover certified by a Chartered Accountant.

Applications in response to this EOI should be submitted in a sealed envelope, superscribed "Expression of Interest (EOI) for Procurement of Wire Bonding Machine" addressed to the Director, Centre of Biomedical Research (CBMR), SGPGIMS Campus, Raebareli Road, Lucknow- 226014 (UP) positively by 03.02.2026 by 3.00 p.m. The offer shall be opened on the same day at 3.30 p.m. There is no need to quote the price at this stage.

"A Technical Committee, constituted by the competent authority shall evaluate the applications and short list the firms for further proceedings. Short listed firms shall be invited for the technical presentation / discussion scheduled on a suitable date, which would be communicated to concerned firms".

If any information furnished in the application is found incorrect at a later stage, the firm shall be liable to be debarred from participation/taking up work in CBMR. CBMR reserves the right to verify the particulars furnished by the applicant independently. CBMR reserves the right to reject any application without assigning any reason.

ADMINISTRATIVE OFFICER